

## STP75NS04Z

# N-channel Clamped - 7mΩ - 80A - TO-220 Fully protected MESH Overlay™ III Power MOSFET

#### **General features**

Туре	V <sub>DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub>
STP75NS04Z	Clamped	$<$ 11m $\Omega$	80A

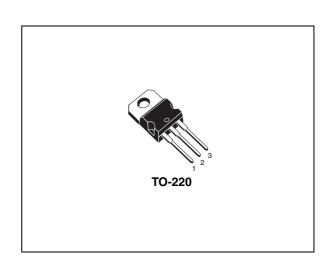
- Low capacitance and gate charge
- 100% avalanche tested
- 175°C maximum junction temperature

### **Description**

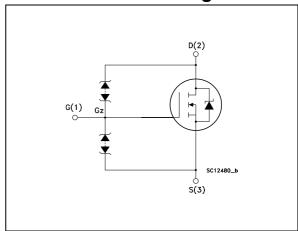
This fully clamped MOSFET is produced by using the latest advanced Company's Mesh Overlay process which is based on a novel strip layout. The inherent benefits of a new technology coupled with the extra clamping capabilities make this product particularly suitable for the harshest operation conditions such as those encoured in power tools. Any other application requiring extra ruggedness is also recommended.

### **Applications**

- Switching application
- Power tools



#### Internal schematic diagram



#### **Order codes**

Part number	Marking	Package	Packaging
STP75NS04Z	P75NS04Z	TO-220	Tube

Contents STP75NS04Z

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STP75NS04Z Electrical ratings

# 1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V <sub>DS</sub>	Drain-source voltage (V <sub>GS</sub> = 0)	Clamped	V
V <sub>DG</sub>	Drain-gate voltage (V <sub>GS</sub> = 0)	Clamped	V
V <sub>GS</sub>	Gate-source voltage	Clamped	V
I <sub>D</sub> <sup>(1)</sup>	Drain current (continuous) at T <sub>C</sub> = 25°C	80	Α
I <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 100°C	63	Α
I <sub>DG</sub>	Drain gate current (continuos)	±50	mA
I <sub>GS</sub>	Gate source current (continuos)	±50	mA
I <sub>DM</sub> <sup>(2)</sup>	Drain current (pulsed)	320	Α
P <sub>TOT</sub>	Total dissipation at T <sub>C</sub> = 25°C	110	W
	Derating factor	0.73	W/°C
V <sub>ESD</sub>	Gate-source ESD (HBM-C=100pF, R=1.5KΩ)	±8	kV
T <sub>j</sub> T <sub>stg</sub>	Operating junction temperature Storage temperature	-55 to 175	°C

<sup>1.</sup> Current limited by wire bonding

Table 2. Thermal data

Symbol	Parameter	Value	Unit
R <sub>thj-case</sub>	Thermal resistance junction-case Max	1.36	°C/W
R <sub>thj-amb</sub>	Thermal resistance junction-ambient Max	62.5	°C/W
T <sub>I</sub>	Maximum lead temperature for soldering purpose	300	°C

Table 3. Avalanche data

Symbol	Parameter	Value	Unit
E <sub>AS</sub>	Single pulse avalanche energy (starting Tj=25°C, I <sub>D</sub> =I <sub>AR</sub> , V <sub>DD</sub> =25V)	470	mJ

<sup>2.</sup> Pulse with limited by safe operating area

Electrical characteristics STP75NS04Z

# 2 Electrical characteristics

( $T_{CASE}$ =25°C unless otherwise specified)

Table 4. On/off states

Symbol	Parameter Test condictions		Min.	Тур.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source breakdown voltage	$I_D = 1$ mA, $V_{GS} = 0$	33			٧
I <sub>DSS</sub>	Zero gate voltage drain current (V <sub>GS</sub> = 0)	V <sub>DS</sub> = 16V			1	μΑ
I <sub>GSS</sub>	Gate body leakage current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ±10V			2	μА
V <sub>GSS</sub>	Gate threshold breakdown voltage	I <sub>GS</sub> = ±100μA	18			٧
V <sub>GS(th)</sub>	Gate threshold voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2	3	4	V
R <sub>DS(on)</sub>	Static drain-source on resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 40A		7	11	mΩ

Table 5. Dynamic

Symbol	Parameter	Test condictions	Min.	Тур.	Max.	Unit
g <sub>fs</sub> <sup>(1)</sup>	Forward transconductance	$V_{DS} = 15V, I_{D} = 15A$		50		S
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input capacitance Output capacitance Reverse transfer capacitance	$V_{DS} = 25V, f = 1 \text{ MHz},$ $V_{GS} = 0$		1860 628 196		pF pF pF
Q <sub>g</sub> Q <sub>gs</sub> Q <sub>gd</sub>	Total gate charge Gate-source charge Gate-drain charge	$V_{DD}$ = 20V, $I_D$ = 80 A, $V_{GS}$ = 10 V (see Figure 13)		50 14 16		nC nC nC

<sup>1.</sup> Pulsed: pulse duration=300µs, duty cycle 1.5%

Table 6. Switching on/off

Symbol	Parameter	Test condictions	Min.	Тур.	Max.	Unit
t <sub>d(on)</sub>	Turn-on delay time Rise time	$V_{DD}$ = 20V, $I_D$ = 40A $R_G$ = 4.7 $\Omega$ $V_{GS}$ = 10V, (see Figure 12)		16 248		ns ns
t <sub>d(off)</sub>	Turn-off delay time Fall time	$V_{DD}$ = 20V, $I_D$ = 40A $R_G$ = 4.7 $\Omega$ $V_{GS}$ = 10V, (see Figure 12)		53 85		ns ns

Table 7. Source drain diode

Symbol	Parameter	Test condictions	Min.	Тур.	Max.	Unit
I <sub>SD</sub>	Source-drain current Source-drain current (pulsed)				80 320	A A
V <sub>SD</sub> <sup>(2)</sup>	Forward on Voltage	I <sub>SD</sub> =80A, V <sub>GS</sub> =0			1.5	٧
t <sub>rr</sub> Q <sub>rr</sub> I <sub>RRM</sub>	Reverse recovery time Reverse recovery charge Reverse recovery current	I <sub>SD</sub> =80A, di/dt = 100A/μs, V <sub>DD</sub> =30V, Tj=150°C (see Figure 17)		53 91 3.4		ns nC A

<sup>1.</sup> Pulse width limited by safe operating area

<sup>2.</sup> Pulsed: pulse duration=300 $\mu$ s, duty cycle 1.5%

Electrical characteristics STP75NS04Z

### 2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

Figure 2. Thermal impedance

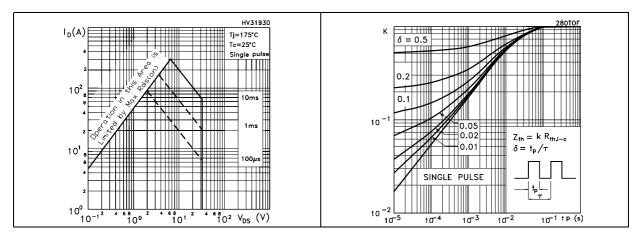


Figure 3. Output characterisics

Figure 4. Transfer characteristics

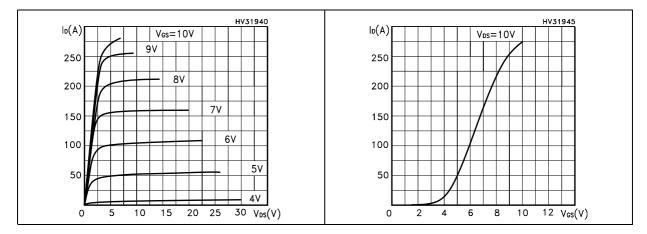
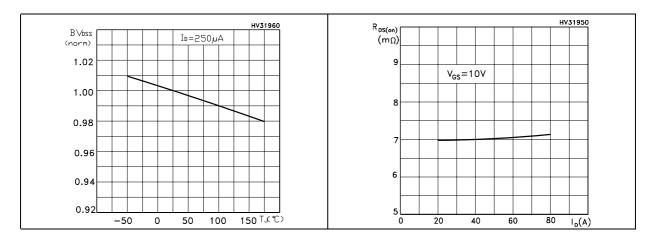


Figure 5. Normalized B<sub>VDSS</sub> vs temperature

Figure 6. Static drain-source on resistance



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Figure 7. Gate charge vs gate-source voltage Figure 8. Capacitance variations

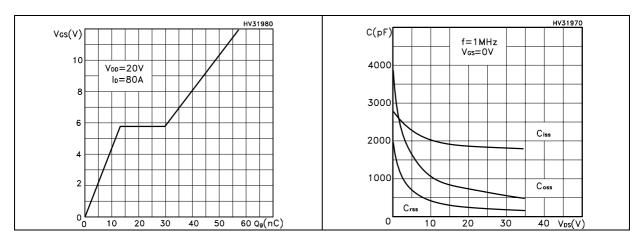


Figure 9. Normalized gate threshold voltage Figure 10. Normalized on resistance vs vs temperature temperature

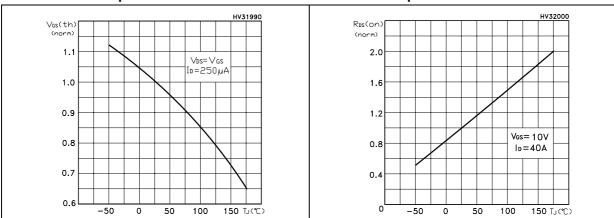
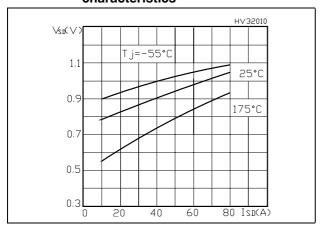


Figure 11. Source-drain diode forward characteristics



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Test circuit STP75NS04Z

### 3 Test circuit

Figure 12. Switching times test circuit for resistive load

Figure 13. Gate charge test circuit

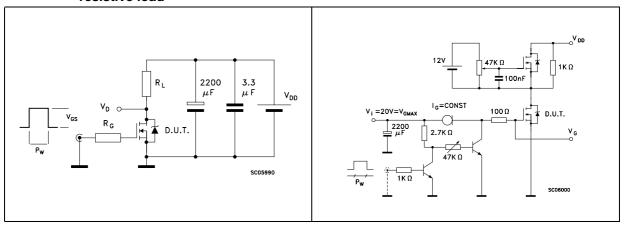


Figure 14. Test circuit for inductive load switching and diode recovery times

Figure 15. Unclamped inductive load test circuit

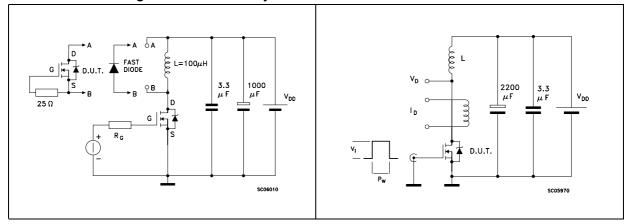
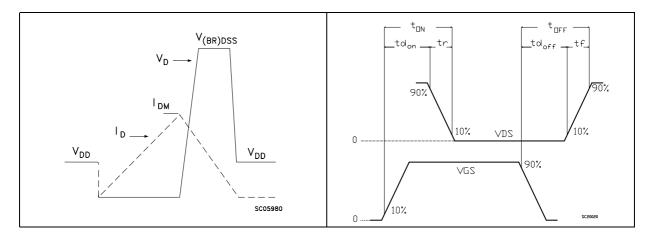


Figure 16. Unclamped inductive waveform

Figure 17. Switching time waveform



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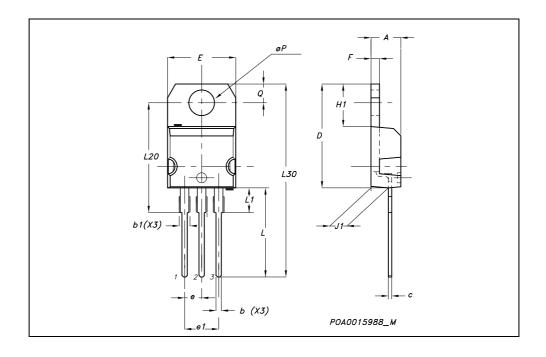
# 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: <a href="https://www.st.com">www.st.com</a>

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#### **TO-220 MECHANICAL DATA**

DIM.		mm.			inch	
DIIVI.	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
Α	4.40		4.60	0.173		0.181
b	0.61		0.88	0.024		0.034
b1	1.15		1.70	0.045		0.066
С	0.49		0.70	0.019		0.027
D	15.25		15.75	0.60		0.620
Е	10		10.40	0.393		0.409
е	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.194		0.202
F	1.23		1.32	0.048		0.052
H1	6.20		6.60	0.244		0.256
J1	2.40		2.72	0.094		0.107
L	13		14	0.511		0.551
L1	3.50		3.93	0.137		0.154
L20		16.40			0.645	
L30		28.90			1.137	
øΡ	3.75		3.85	0.147		0.151
Q	2.65		2.95	0.104		0.116



STP75NS04Z Revision history

# 5 Revision history

Table 8. Revision history

Date	Revision	Changes
06-Jun-2006	1	First release

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